

Title (en)  
Multilayer printed circuit board laminate and process for manufacturing the same

Title (de)  
Mehrlagen-Leiterplatten-Verbundkörper sowie Verfahren zu dessen Herstellung

Title (fr)  
Laminé de panneau à circuit imprimé multicouche et son procédé de fabrication

Publication  
**EP 1363483 A3 20051005 (DE)**

Application  
**EP 03010758 A 20030514**

Priority  
DE 10221553 A 20020514

Abstract (en)  
[origin: EP1363483A2] The method involves providing a circuit board blank (1) comprising a substrate (2) and at least one electrically conductive layer (3) of a thickness that is suitable for carrying power currents. The thickness of part of the conductive layer (3) is reduced to create a signal conduction layer. The conductive layer has a thickness DL, where 150 mumat mostDLapproximately600 mum, preferably DL400 mum. An Independent claim is included for a multilayer circuit board module.

IPC 1-7  
**H05K 3/06**; **H05K 1/02**

IPC 8 full level  
**H05K 1/02** (2006.01); **H05K 3/06** (2006.01); **H05K 1/00** (2006.01); **H05K 3/42** (2006.01)

CPC (source: EP)  
**H05K 1/0265** (2013.01); **H05K 3/06** (2013.01); **H05K 1/0393** (2013.01); **H05K 3/427** (2013.01); **H05K 2201/0394** (2013.01); **H05K 2201/09736** (2013.01); **H05K 2203/1476** (2013.01); **H05K 2203/302** (2013.01)

Citation (search report)

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- [AY] US 6222136 B1 20010424 - APPELT BERND KARL-HEINZ [US], et al
- [Y] DE 4208765 A1 19930805 - MECANISMOS AUX IND [ES]
- [XY] PATENT ABSTRACTS OF JAPAN vol. 018, no. 673 (E - 1647) 19 December 1994 (1994-12-19)
- [XA] PATENT ABSTRACTS OF JAPAN vol. 014, no. 032 (E - 876) 22 January 1990 (1990-01-22)
- [XA] DATABASE WPI Week 198738, Derwent World Patents Index; AN 1987-267256, XP002340294
- [A] PATENT ABSTRACTS OF JAPAN vol. 018, no. 590 (E - 1628) 10 November 1994 (1994-11-10)
- [A] PATENT ABSTRACTS OF JAPAN vol. 2000, no. 25 12 April 2001 (2001-04-12)

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Designated contracting state (EPC)  
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DOCDB simple family (publication)  
**EP 1363483 A2 20031119**; **EP 1363483 A3 20051005**; DE 10221553 A1 20031127

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